









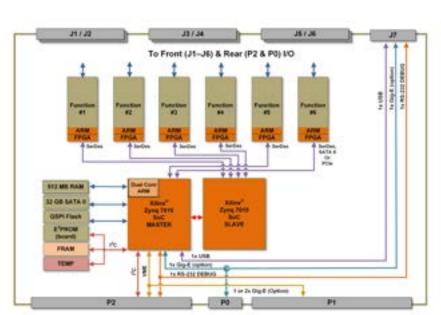
64ARM1 6U VME Single Board Computers 6U VME ARM Cortex-A9 SBC

6U VME ARM SBC with six I/O and communications function module slots — Over 100 different modules to choose from

NAI's 64ARM1 is a 6U VME ARM® Cortex®-A9 - based, Single Board Computer (SBC) that can be configured with up to six smart function modules. Ideally suited for rugged defense, commercial aerospace, and industrial applications, the 64ARM1 delivers off-the-shelf solutions that accelerate deployment of SWaP-optimized systems. The ARM® Cortex®-A9 processor is a low power, cost-sensitive, multi-core processor delivering exceptional levels of performance and power efficiency with all the functionality required in rugged, embedded SWaP-optimized programs for the defense and aerospace industries.

The 64ARM1 includes BSP and SSK support for Wind River® VxWorks®, and for Xilinx® PetaLinux. In addition, SSKs are supplied with source code and board-specific library I/O APIs to facilitate system integration.





Features

- ARM® Cortex®-A9 Dual Core 800MHz Processor
- 512 MB DDR3 SDRAM
- Up to 32 GB SATA II NAND Flash (256 GB expansion option in slot #6)
- PCle interface to function module slot #6 for 2 additional Gig-E ports
- < 8 W MB power dissipation
- Front and/or rear I/O

- COSA® Architecture
- · 100+ modules to choose from
- Up to 6 independent smart I/O function modules supported
- Independent x1 SerDes interface to each function module slot
- 2x 10/100/1000 Base-T Ethernet; 2 to rear or 1 to rear and 1 to front I/O
- 1x USB 2.0 port to rear or front I/O
- 1x RS-232 to front or rear I/O
- I2C Bus to rear I/O

- Wind River®, VxWorks® and Xilinx® PetaLinux OS support
- Continuous Background Built-in-Test (BIT)
- Intelligent I/O library support included
- VICTORY Interface Services (Contact factory)
- Commercial or rugged applications
- Operating temp: 0° C to +70° C or Rugged -40° C to +85° C



Select up to 6 independent functions for your application

			I/O Modules		
Function	Module	Description	Function	Module	Description
Analog-to-Digital	AD1	12 CH. A/D, ±10 V, Dedicated, 256 kHz (max), Sigma- Delta		DF1	16 CH. Differential I/O, Input: -10 V to +10 V (422), -7 V to +1 V (485) Output:25 V to +5 V
	AD2	12 CH. A/D, ±100 V (max), Dedicated, 256 kHz (max), Sigma-Delta	Digital IO - Differential Transceiver	DF2	16 CH. 16 Channel Enhanced Differential I/O
	AD3	12 CH. A/D, ±25 mA, Dedicated, 256 kHz (max), Sigma-Delta		DT1	24 CH. Discrete I/O, 0-60 VDC Input/Output, Max Iout 500 m 2 A, Source/Sink (out)
	AD4	16 CH. A/D, ± 10 V, Multiplexed, 500 KHz Agg / 8 Ch, SAR		DT2	16 CH. Discrete I/O, ±80 V Input/Output, Max lout 600 mA, Isolated/Ch Switch (out)
	AD5	16 CH. A/D, ± 50 V, Multiplexed, 500 KHz Agg / 8 Ch, SAR	Discrete IO - Multichannel,Programmable	DT3	4 CH. Discrete Hi & Lo Side Switch Output @ 65V/2A (max), external individual supplied VCC & VSS per channel pair
	AD6	16 CH. A/D, ± 100 V, Multiplexed, 500 KHz Agg / 8 Ch, SAR		DT4	24 CH. Enhanced DT1
	ADE	16 CH. A/D, ±10 V, Individual 16-bit SAR, 200 kHz max., Simultaneous Sampling		DT5	16 CH. Enhanced DT2
	ADF	16 CH. A/D, ±100 V, Individual 16-bit SAR, 200 kHz max., Simultaneous Sampling		RY1	4 CH. Relay, 220V/2A @ 60W/62.5VA (Max), Non Latching
Digital-to-Analog	DA1	12 CH. D/A, ± 10 V, 25 mA Per Channel, Current or Voltage Control	Relay	RY2	4 CH. Relay, 220V/2A @ 60W/62.5VA (Max), Latching
	DA2	16 CH. D/A, ± 10 V, 10 mA Per Channel, No Current Control	Digital IO - TTL,CMOS	TL1	24 CH. TTL I/O, Standard Functionality, Programmable
	DA3	4 CH. D/A, ±40 V, ±100 mA, Voltage or Current Output	2.g.tai 10 112,01100	TL2	24 CH. TTL I/O, Enhanced Functionality, Programmable
	DA4	4 CH. D/A, ± 20 to ± 80, 10 mA, Voltage Control Only	Variable Reluctance	VR1	8 CH. Variable Reluctance Signal Input and General-Purpose Pulse Counter, ±100 V, 100 kHz (max)
	DA5	4 CH. D/A, High-Voltage/High-Current Half-Bridge (2 Channels Full-Bridge) External VCC Sourced Outputs			
		Measureme	nt & Simulation Modules		
Function	Module	Description	Function	Module	Description
AC Reference	AC2	2 CH. AC Reference Source, 47 Hz - 20 KHz, ± 3% Acc, 2 – 28 Vrms, 6 VA (Max/Ch) Power	LVDT RVDT Measurement and Simulation	LD5	4 CH. LVDT/RVDT to Digital, 28-90 Vrms Input, 2-115 Vrms Exc, 47 Hz - 1 KHz Freq
	AC3	2 CH. AC Reference Source, 47 Hz - 2.5 KHz, ± 3% Acc, 28 – 115 Vrms, 6 VA (Max/Ch) Power	Synchro Resolver Measurement and	DSx (DRx)	1 - 3 CH. Digital to Synchro/Resolver, 2 - 90 VLL, 2 - 1115 Vrms Exc, 47 Hz - 20 kHz Freq
LVDT RVDT Measurement and Simulation	DLx	1 - 3 CH. Digital to LVDT/RVDT, 2 - 90 Vrms Full Scale, 2 - 115 Vrms Exc, 47 Hz - 20 kHz Freq	Símulation	SDx	4 CH. Synchro/Resolver to Digital, 2 - 90 Vrms Input, 2 - 115 Vrms Exc, 47 Hz to 20 kHz Freq
	LD1	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2-115 Vrms Exc, 47 Hz -1 KHz Freq		RT1	8 CH. Resistance Temperature Detectors (RTD), 2, 3, or 4 wire, 16 Bit Res, 16.7 Hz/Ch
	LD2	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2-115 Vrms Exc, 1 KHz - 5 KHz Freq	Thermocouple and RTD Measurement	TC1	8 CH. Thermocouple, 4.17 - 470 Hz, ±100 mV A/D
	LD3	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2-115 Vrms Exc, 5 KHz - 10 KHz Freq		TR1	8 CH. Thermocouple (TCx) & Resistance Temperature Detectors (RTD), programmable per channel
	LD4	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2-115 Vrms Exc, 10 KHz - 20 KHz Freq	Strain Gauge Measurement	<u>SG1</u>	4 CH. Strain Gauge, 4.7 Hz - 4.8 KHz, Measurement, Conventional 4-Arm Bridge



Communication Modules										
Function	Module	Description		Function	Module	Description				
ARINC Communications	AR1	12 CH. ARINC 429, 100 KHz or 12.5 KHz, RX/TX, 256 Word Tx/Rx Buffer			<u>FTD</u>	1 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM, Direct Coupled				
	AR2	1 CH. ARINC 568 (CH-1, RX & TX) & 1 Channel ARINC 579 (CH-2, Programmable RX or TX), 1024-Word TX & RX Buffers per Ch.		MIL-STD-1553B	<u>FTE</u>	2 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Direct Coupled				
CANBus Communications	CB1	8 CH. CANBus, CAN 2.0 A/B, 16 K RX/TX Buffer, 1 Mb/s Max Data Rate			FTF	4 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Direct Coupled				
	CB2	8 CH. CANBus, J1939, 16 K RX/TX Buffer, 500 kb/s Max Data Rate		MIL CTD 4700	FTJ	1 CH. MIL-STD-1760 (1553), BC, RT, BM, BM/RT, 128 KB RAM, Transformer Coupled				
	CB3	8 CH. CANBus, CAN 2.0 A/B (CB1) or J1939 (CB2) protocol layer programmable per channel		MIL-STD-1760	<u>FTK</u>	2 CH. MIL-STD-1760 (1553), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Transformer Coupled				
Ethernet NIC Interface	<u>EM1</u>	2 CH. Dual Ethernet I/F, Intel 82850, 10/100/1000			SC1	4 CH. Serial, RS-232/422/423 (MIL-STD-188C)/485, Non Isolated				
MIL-STD-1553B	<u>FTA</u>	1 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM, Transformer Coupled		Overland	SC3	8 CH. (max) RS-232/422/485 Serial Communications or GPIO, Programmable, Non-isolated				
	FTB	2 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Transformer Coupled		Serial Communications	SC5	4 CH. RS-232/422/485 communications, isolated per channel and from SYS GND				
	FTC	4 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Transformer Coupled			SC6	4 CH. RS-232/422/485 communications, individual SYS GND provided per channel (non-isolated)				
Storage										
Function	Module	Description		Function	Module	Description				
SATA Solid State Drive (SSD)	FM2	1 CH. 480 GB MLC SATA Flash, extended temp -40°C to 85°C operation		SATA Solid State Drive (SSD)	FM9	1 CH. 1.92 TB SATA TLC NAND Flash, Extended Temperature Operation				
	FM8	1 CH. 1 TB SATA TLC NAND Flash, Extended Temperature Operation								
Combination Modules										
Function	Module	Description		Function	Module	Description				
Combo	<u>CM5</u>	2 CH. Dual-redundant MIL-STD-1553 & 8 Channel ARINC 429/575, 100 KHz or 12.5 KHz, RX or TX, 256 Word Tx/Rx Buffer		Combo	CM8	2 CH. Dual-redundant MIL-STD-1553 & 12 Channel Discrete I/O, 0-60 VDC Input/Output, Max lout 500 mA - 2 A, Source/Sink (out)				

Architected for Versatility

NAI's Configurable Open Systems Architecture™ (COSA®) offers a choice of over 100 smart I/O, communications, or Ethernet switch functions, providing the highest packaging density and greatest flexibility of ruggedized embedded product solutions in the industry. Preexisting, fully-tested functions can be combined in an unlimited number of ways quickly and easily.

One-Source Efficiencies

Eliminate man-months of integration with a configured, field-proven system from NAI. Specification to deployment is a seamless experience as all design, state-of-the-art manufacturing, assembly and test are performed - by one trusted source. All facilities are located within the U.S. and optimized for high-mix/low volume production runs and extended lifecycle support.

Product Lifecycle Management

From design to production and beyond, NAI's product lifecycle management strategy ensures the long-term availability of COTS products through configuration management, technology refresh and obsolescence component purchase and storage.

Made in the USA Centified Small Business

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